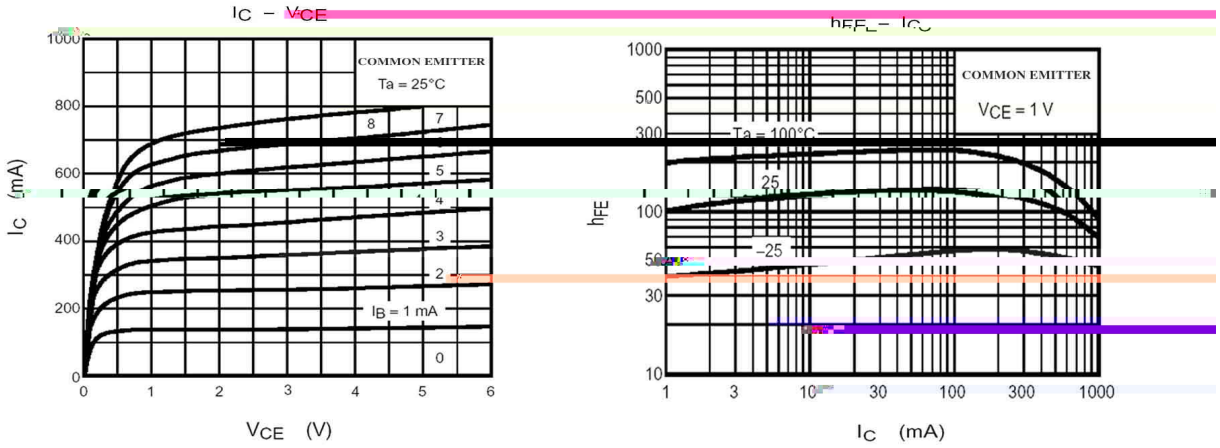
| v ̈Ọ<br>Parameter | ↿ N<br>Symbol | ̈Ọ Ö<br>Rating | D Ꮋ<br>Unit |
|---|---|---|---|
| Collector to Base Voltage | $V_{CBO}$ | 35 | V |
| Collector to Emitter Voltage | $V_{CEO}$ | 30 | V |
| Emitter to Base Voltage | $V_{EBO}$ | 5.0 | V |
| Collector Current - Continuous | $I_C$ | 800 | mA |
| Emitter Current - Continuous | $I_E$ | -800 | mA |
| Collector Power Dissipation | $P_C$ | 600 | mW |
| Junction Temperature | $T_j$ | 150 | |
| Storage Temperature Range | $T_{stg}$ | -55 150 | |

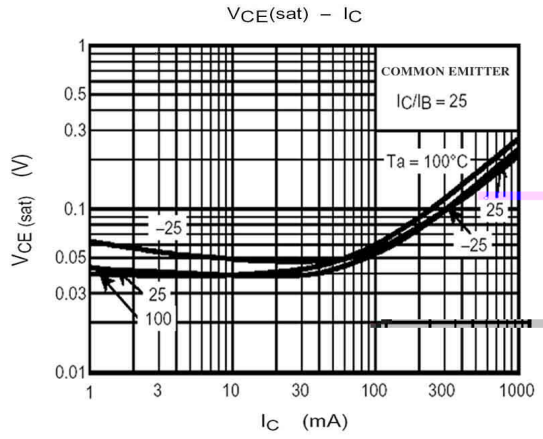
| v ̈Ọ<br>Parameter | ↿ N<br>Symbol | ⅄ ; ̇ Ţ<br>Test Conditions | ѡ ṇ Ö<br>Min | Ɛ ȝ Ö<br>Typ | ѡ ᶻ Ö<br>Max | D Ꮋ<br>Unit |
|---|---|---|---|---|---|---|
| Collector to Base Breakdown Voltage | $V_{CBO}$ | $I_C$=10mA $I_E$=0 | 30 | | | V |
| Collector Cut-Off Current | $I_{CBO}$ | $V_{CB}$=35V $I_E$=0 | | | 0.1 | μA |
| Emitter Cut-Off Current | $I_{EBO}$ | $V_{EB}$=5.0V $I_C$=0 | | | 0.1 | μA |
| DC Current Gain | $h_{FE(1)}$ | $V_{CE}$=1.0V $I_C$=100mA | 100 | | 320 | |
| | $h_{FE(2)}$ | $V_{CE}$=1.0V $I_C$=700mA | 35 | | | |

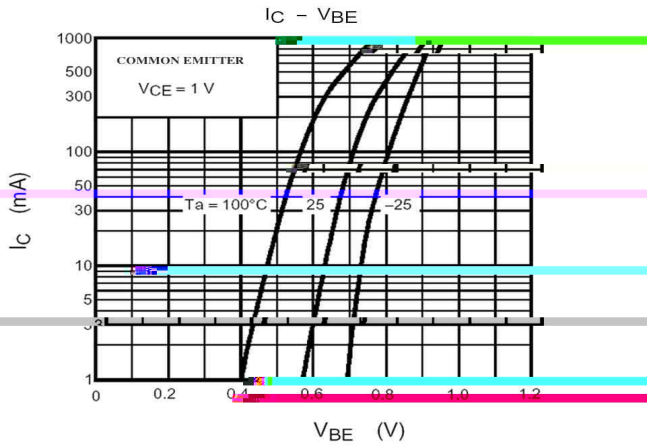
## / Electrical Characteristic Curve

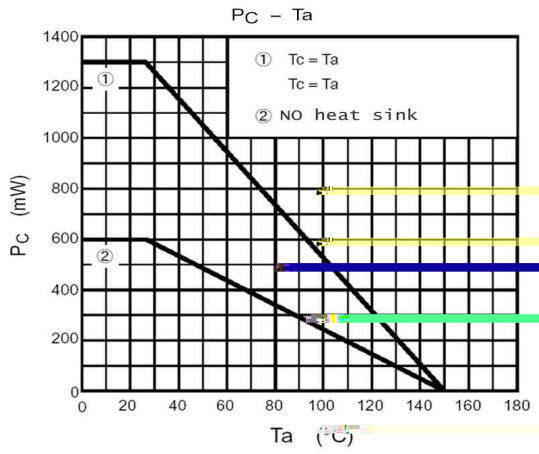




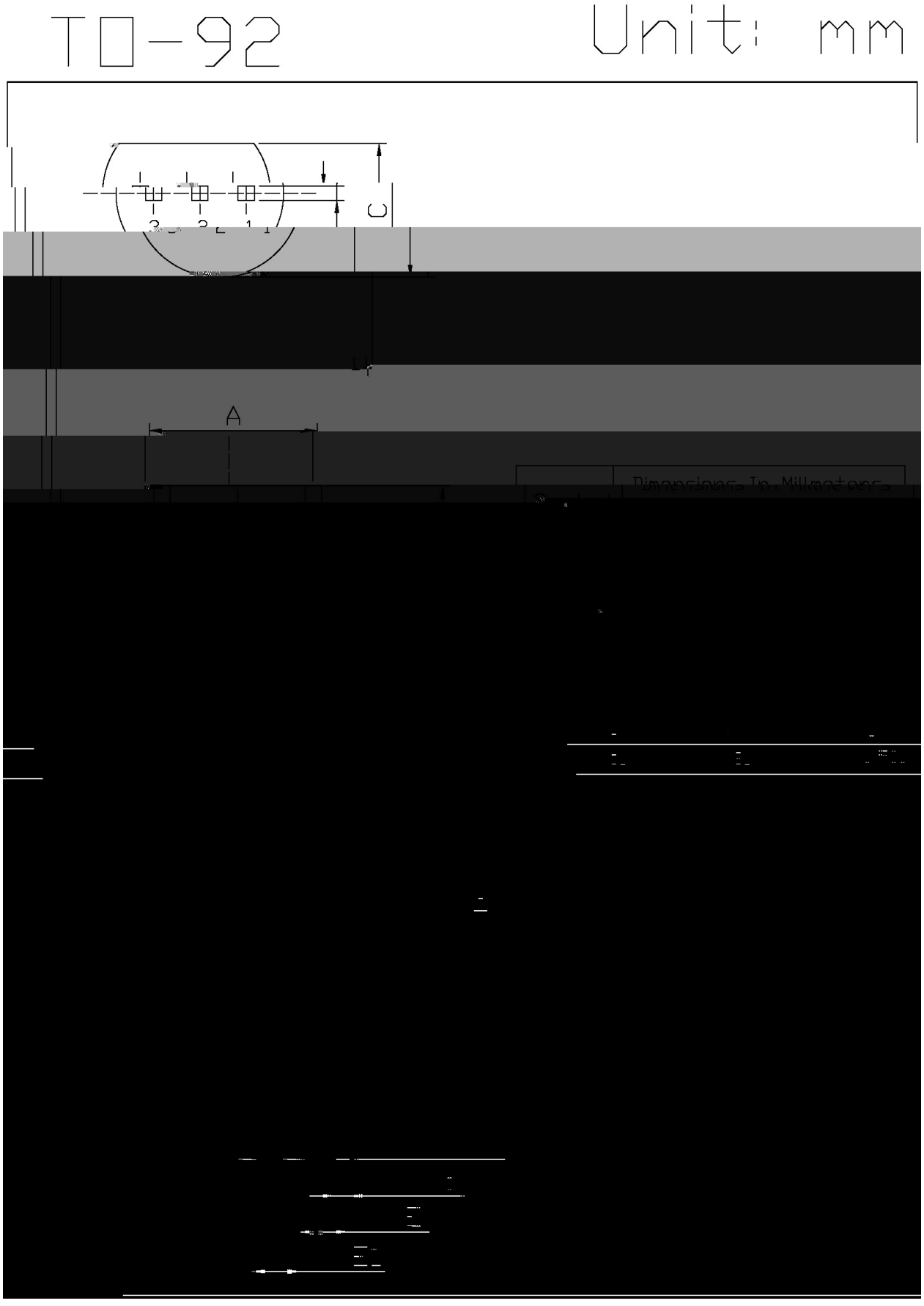


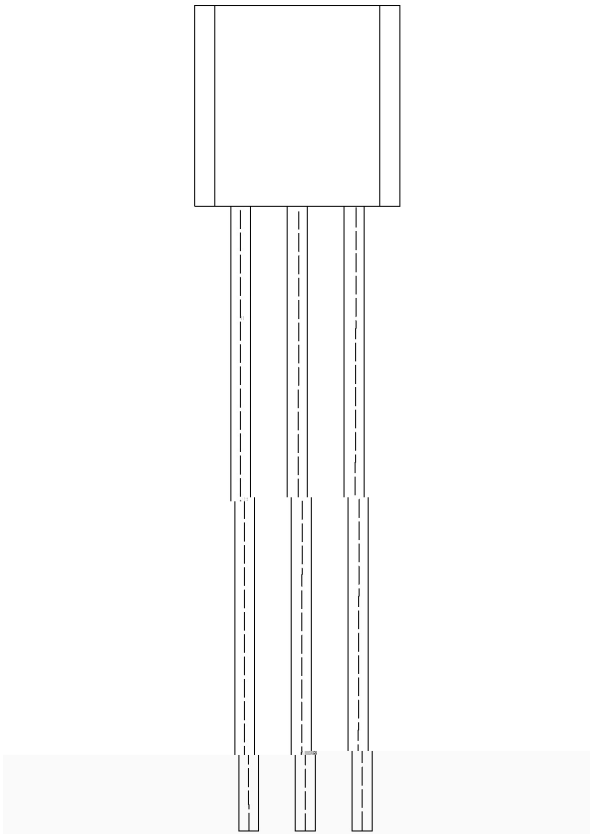


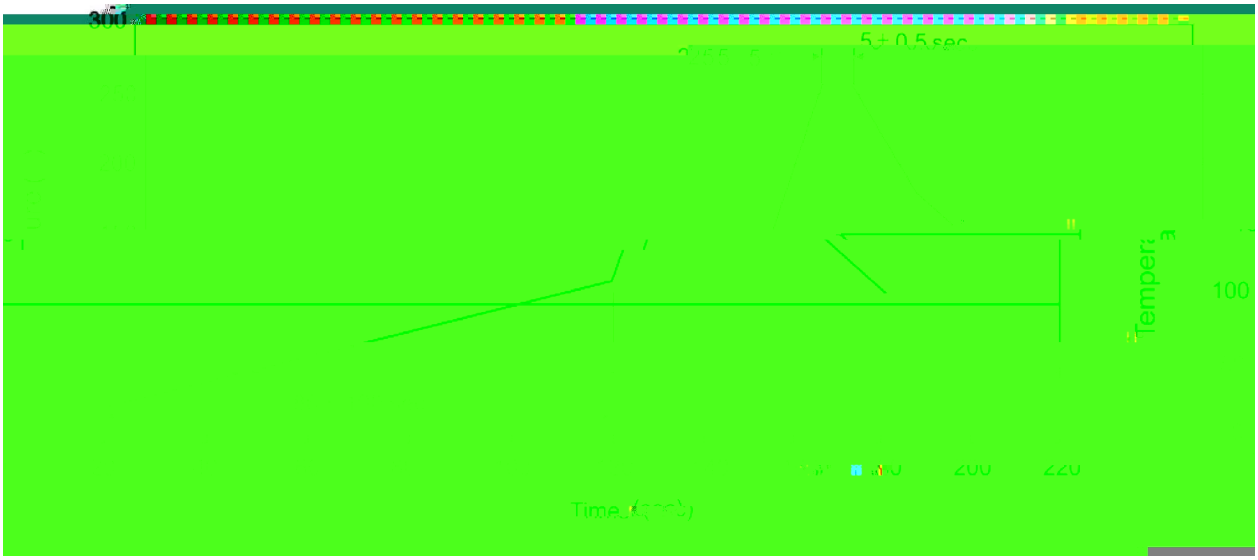



## / Package Dimensions





## ( ) / Temperature Profile for Dip Soldering(Pb-Free)




ب ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ө □ ỷ 255 ° 5 ł ı ˋH ڑ ˋY ﾊ ㎛ 5 ° 0.5sec;

3 ì ˙ ﾘ ˛ ɔ ෯ ỷ ㎛ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:255 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

## / Resistance to Soldering Heat Test Conditions

| | | | |
|---|---|---|---|
| □ ỷ χ 270 ° 5 ł | ˋH ڑ χ 10 ° 1 sec. | Temp:270±5 | Time:10±1 sec |

## / Packaging SPEC.

ˈQ ţ ﾔ Ł / BULK

| Package Type | Units | Dimension | (unit mm3) |
|---|---|---|---|